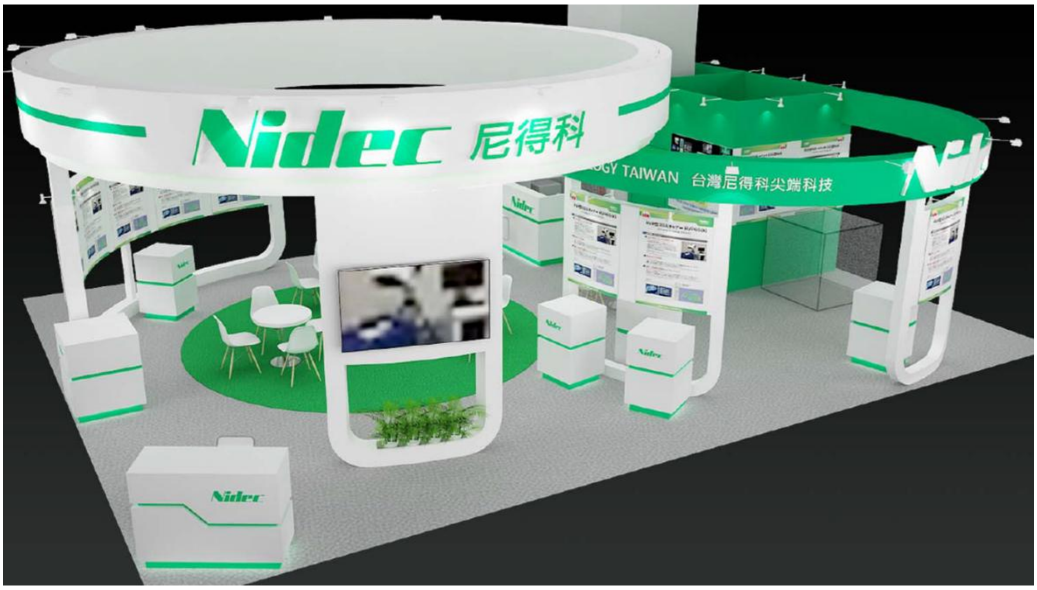
Nidec Advance Technology Corporation

September 05, 2025

Nidec Advance Technology to Exhibit Products at SEMICON TAIWAN 2025

Nidec Advance Technology Corporation ("Nidec Advance Technology" or the "Company") announced today that it will exhibit products at SEMICON TAIWAN 2025, a largest exhibition of its kind in Asia for companies in the semiconductor to display their state-of-the-art technologies and innovations, to be held from Wednesday, September 10 – Friday, September 12, 2025 at Taiwan Nangang International Exhibition Center.



This year, under the theme, "*Leading with Collaboration. Innovating with the World*," this most influential semiconductor-related event in Taiwan will host more than 1,100 from 56 countries around the world. At present, amid the surging demand for AI and high-performance computing (HPC), the semiconductor industry is facing the age of "Hyper Moore's Law." As their processing capacity increases, semiconductor-related products are becoming increasingly miniaturized while their installation processes are becoming more and more complex. These trends are necessitating an urgent development of new inspection technologies.

At this upcoming event, based on the theme, "ONE STOP SOLUTIONS of AI server/EVs," Nidec Advance Technology will showcase its latest solutions based on the Company's probe card (a wafer inspection jig), together with its excellent optical inspection, electrical inspection, and probing technologies, and offer cutting-edge inspection solutions in all areas of wafer, chip, substrate, and package for state-of-the-art semiconductor packages. The Company will also introduce most-advanced technologies and products related to power semiconductor inspection equipment and transfer robots, both of which are drawing attention nowadays.

About SEMICON TAIWAN 2025:

- Period: Wednesday, September 10 – Friday, September 12, 2025
- Venue: Taiwan Nangang International Exhibition Center (TaiNEX 1)
- Booth: K2786, Hall 1

Nidec Advance Technology's exhibits will include:

- High-precision 2D MEMS probe card with reduced noise-caused effects
- TC probe for -40 – 200ºC measurements
- MEMS FLEX probe card with the minimum 60μm pitch for cutting-edge devices
- Chamber head probe card for high voltages and temperatures
- 3H+ probe for high temperature, voltages, and densities
- NSW Series (high-precision optical wafer inspection equipment)
- RWi Series (optical 2D/3D inspection equipment for wafer bumps)
- Optical 2D/3D inspection solutions for TGV
- GATS-7886 (FOPLP/RDL conduction inspection system)
- NATS-1000 Series (power semiconductor inspection system)
- TDAS-Series (EV test bench)
- E-Transport Simulator (xEV modelling simulator)
- AVR SMV 3000 (the wafer transfer robot system jointly developed with Nidec Instruments Corporation)

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